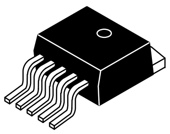
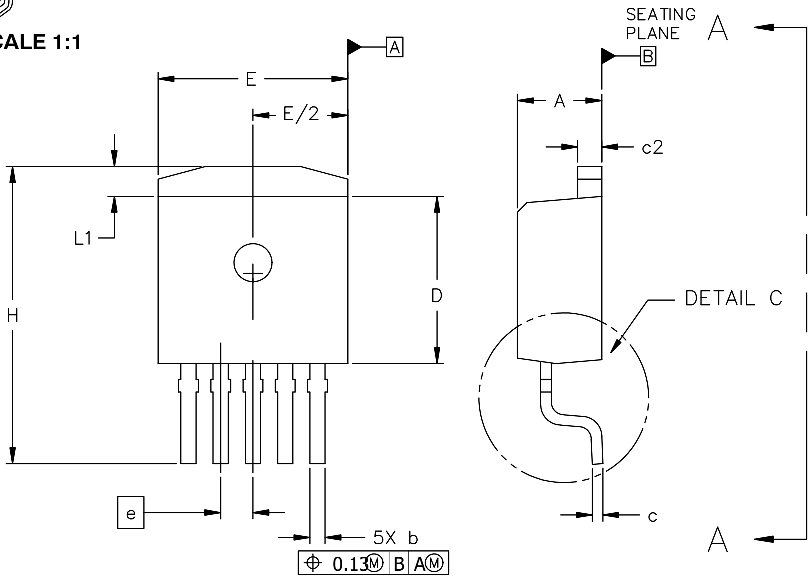


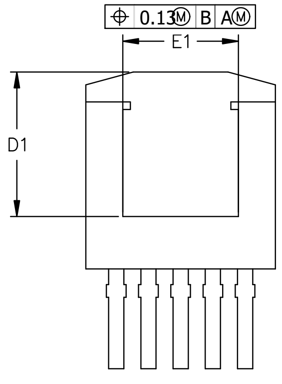
SCALE 1:1

D²PAK–5 8.89x10.20x0.12, 1.70P
CASE 936AC
ISSUE B

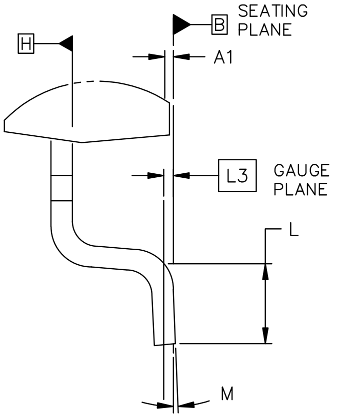
DATE 27 APR 2026



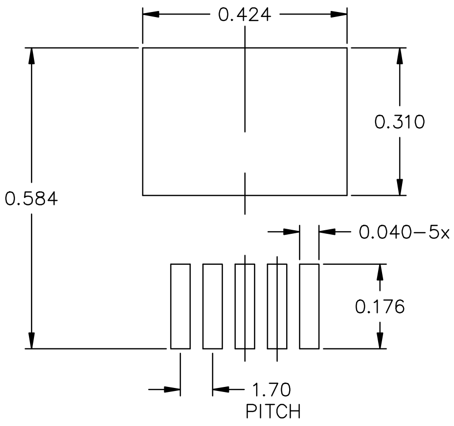
DIM	MILLIMETERS MIN	NOM	MAX
A	4.320	4.445	4.570
A1	0.000	0.125	0.250
b	0.660	0.785	0.910
c	0.430	0.545	0.660
c2	1.140	1.270	1.400
D	8.250	8.890	9.530
D1	6.350	---	---
E	9.650	10.205	10.760
E1	5.080	---	---
e	1.700 BSC		
H	14.730	15.240	15.750
L	2.290	2.540	2.790
L1	---	---	1.680
L3	0.250 BSC		
M	0°	4°	8°



VIEW A–A



DETAIL C

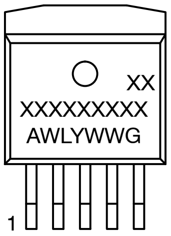


RECOMMENDED MOUNTING FOOTPRINT

NOTES:
1. CONTROLLING DIMENSION: MILLIMETERS [mm].
2. ENCAPSULANT: EPOXY.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.005 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1. DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THE THERMAL PAD.

*For additional information on our Pb–Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**D²PAK–5 8.89x10.20x0.12, 1.70P**		**PAGE 1 OF 1**